



Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment

Marketing Name / Model

[List multiple models if applicable.]

HPE 12900E 48p 40GbE QSFP+ HB Mod (JH359A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sqcm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0

Components, parts and materials containing radioactive substances		0
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2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#
Socket spanner	M3

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the film 1, film 2 and part 3;
2. Unscrew the screws on part 4, and then remove part 4;
3. Remove part 4-1 from part 4;
4. Unscrew the screws on part 5, and then remove part 5;
5. Unscrew the screws on part 6, and then remove part 6;
6. Unscrew the screws on pcb 7, and then remove pcb 7;
7. Unscrew the screws on pcb 8, and then remove pcb 8;
8. Unscrew the screws on heatsink 9, and then remove heatsink 9;
9. Unscrew part 10, and then remove part 10;
10. Unscrew part 11, and then remove part 11;
11. Unscrew part 12, and then remove part 12;
12. Unscrew the screws on pcb 13, and then remove pcb 13 from part 14;
13. Push part 13-1, and then remove heatsink 13-2 from pcb 13;
14. Unscrew the screws on pcb 13, and then remove part 13-3 and part 13-4 from pcb 13;
15. Push part 13-1, and then remove heatsink 7-1 from pcb 7;
16. Push part 13-1, and then remove heatsink 8-1 and heatsink 8-2 from pcb 8;

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

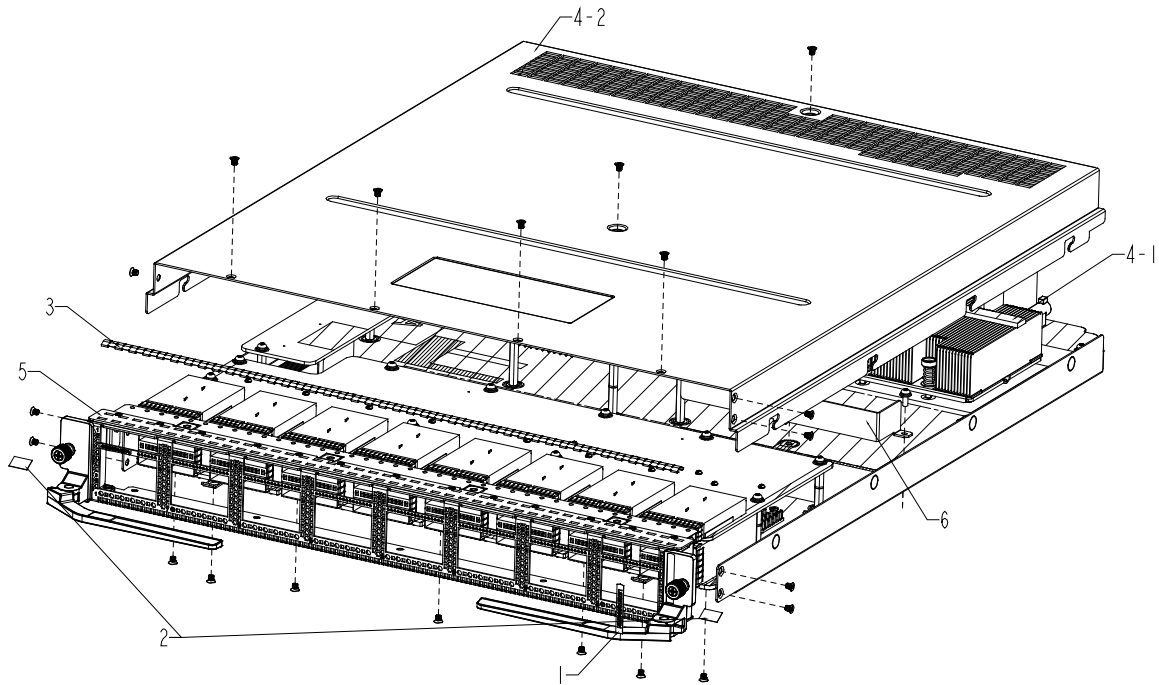


Figure 1 Treatments to the product

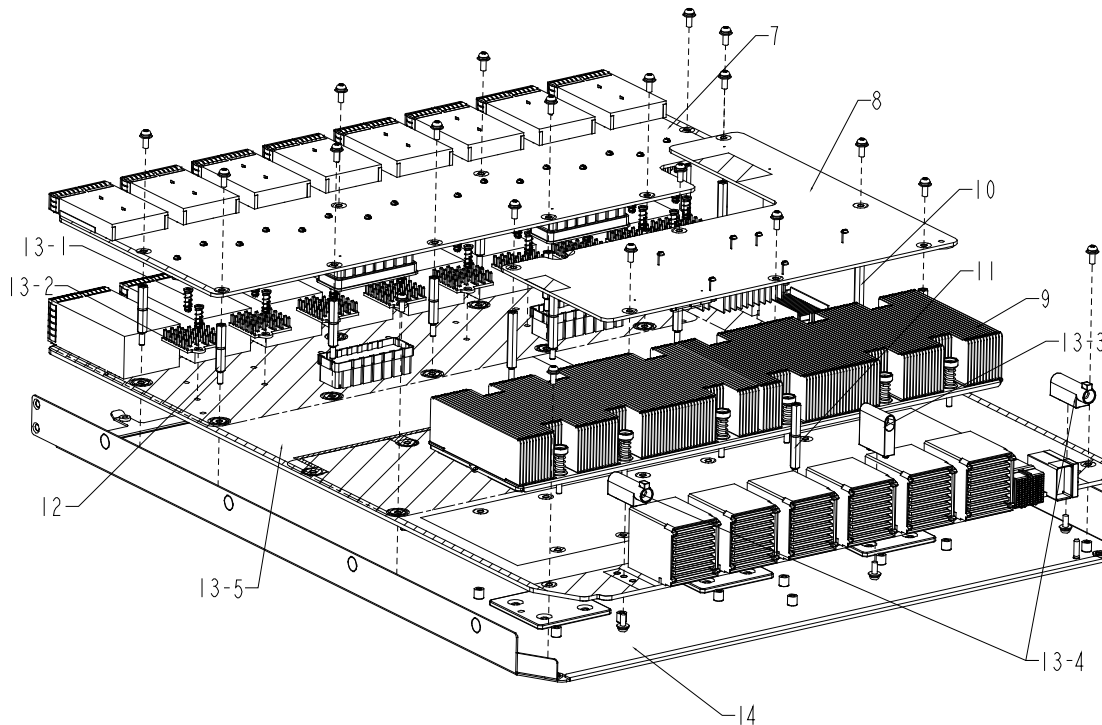


Figure 2 Treatments to the product

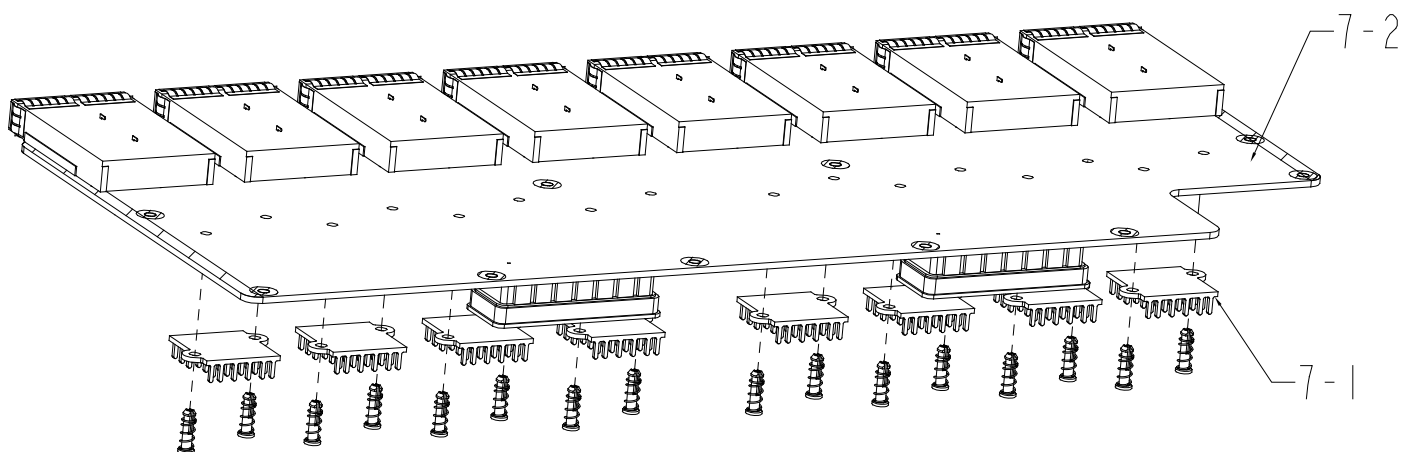


Figure 3 Treatments to pcb 7

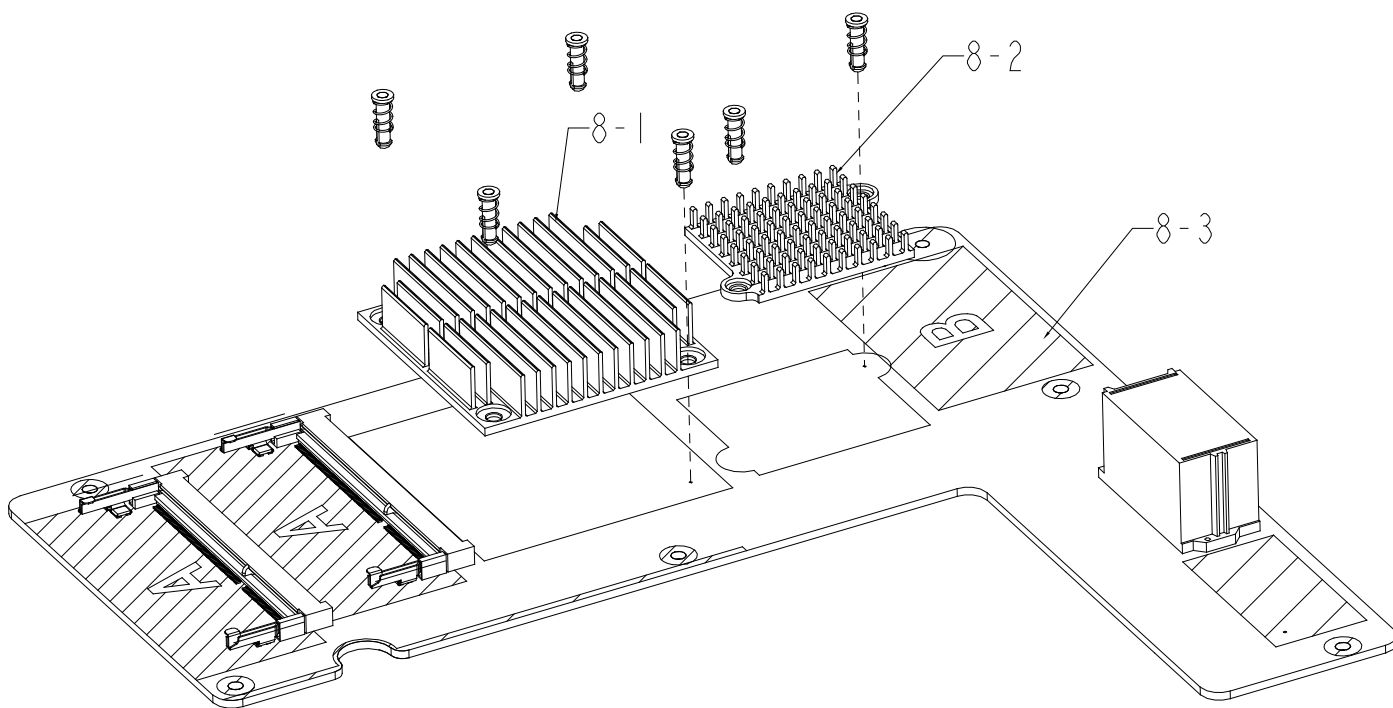


Figure 4 Treatments to pcb 8

3.3 Material of the facility built

Facility	Components	Material	Weight(g) *PCS	Weight percentage	Selective treatment for materials and components	Details
3		Be ,Cu	3*1	0.03%		Be ,Cu recycling
4						
	4-1	Pla	1*1	0.01%		Pla recycling
	4-3	Fe	1587*1	17.51%		Fe recycling
5		Fe ,Zn	471*1	5.20%		Fe, Zn recycling
6		Fe	24*1	0.26%		Fe recycling
7						
	7-1	Al	3*8	0.26%		Al recycling
	7-2	Complex PCB	459*1	5.06%	The surface of PCB is greater than 10 square centimeters;	
8						
	8-1	Al	42*1	0.46%		Al recycling
	8-2	Al	9*1	0.10%		Al recycling
	8-3	Complex PCB	248*1	2.74%	The surface of PCB is greater than 10 square centimeters;	
9		Fe, Cu	2247*1	24.79%		Fe, Cu recycling
10		Fe	5*7	0.39%		Fe recycling
11		Fe	6*2	0.13%		Fe recycling
12		Fe	4*10	0.44%		Fe recycling
13						
	13-1	Pla, Fe	1*42	0.46%		Pla, Fe recycling
	13-2	Al	3*10	0.33%		Al recycling
	13-3	Zn	23*1	0.25%		Zn recycling
	13-4	Zn	16*2	0.35%		Zn recycling
	13-5	Complex PCB	1976*1	21.80%	The surface of PCB is greater than 10 square centimeters;	
14		Fe, Al	1758*1	19.40%		Fe, Al recycling

4. Revised record

Date	Version	Author	Modify content
2016.03.27	V0	Chen Linwei	Initial version
2016.04.28	V1	Chen Linwei	Add part "0231A4X6"